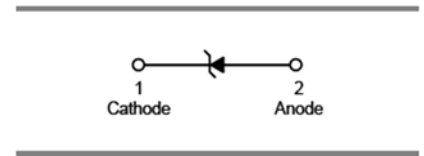


# Surface Mount Zener Diode



SOD-123

## Features:

- Planar Die Construction
- 500mW Power Dissipation
- General Purpose, Medium Current
- Ideally Suited For Automated Assembly Processes

## Applications:

- Zener diode
- Ultra-small surface mount package

## Maximum Rating @ T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Forward voltage @ I <sub>F</sub> = 10mA	V <sub>F</sub>	0.9	V
Power dissipation	P <sub>D</sub>	500	mW
Thermal resistance, junction to ambient air	R <sub>θjA</sub>	350	°C/W
Junction temperature	T <sub>j</sub>	150	°C
Storage temperature range	T <sub>stg</sub>	-65 to +150	°C

**Note :** Device mounted on ceramic PCB; 7.6mm × 9.4mm × 0.87mm with pad areas 25mm<sup>2</sup>.  
Tested with pulses, T<sub>p</sub> ≤ 1ms.

## Electrical Characteristics @ T<sub>A</sub> = 25°C unless otherwise specified

Type Number	Type Code	Zener Voltage Range			Test Current	Maximum Zener Impedance		Maximum Reverse Leakage Current	
		V <sub>Z</sub> @I <sub>ZT</sub>				Z <sub>ZT</sub> @I <sub>ZT</sub>	Z <sub>ZK</sub> @I <sub>ZK</sub> = 0.25mA	I <sub>R</sub>	@V <sub>R</sub>
		Nom(V)	Min(V)	Max(V)	mA	Ω		μA	V
MMSZ5236B	F1	7.5	7.13	7.88	20	6	500	3	6



# Surface Mount Zener Diode



Typical Characteristics @  $T_A = 25^\circ\text{C}$  unless otherwise specified

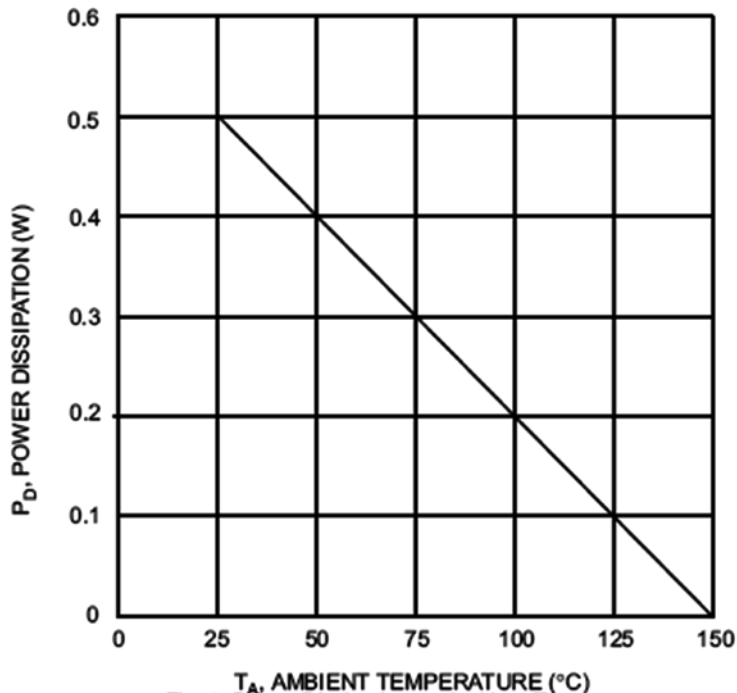
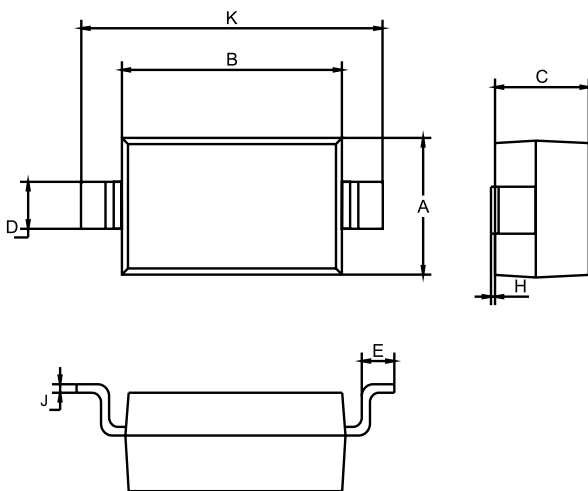


Fig. 1 Power Dissipation vs Ambient Temperature

## Package Outline

Plastic surface mounted package



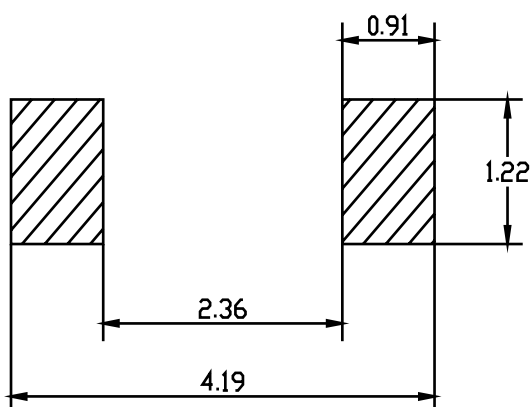
SOD-123		
Dim	Min	Max
A	1.4	1.8
B	2.55	2.85
C	1.15 Typical	
D	0.5	0.6
E	0.3	0.4
H	0.02	0.10
J	0.1 Typical	
K	3.55	3.85
All Dimensions in mm		



# Surface Mount Zener Diode



## Soldering Footprint



Dimensions : Millimetres

## Package Information

Device	Package	Shipping
MMSZ5236B-7-F	SOD-123	3000/Tape & Reel

## Part Number Table

Description	Part Number
Surface Mount Zener Diode	MMSZ5236B-7-F

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